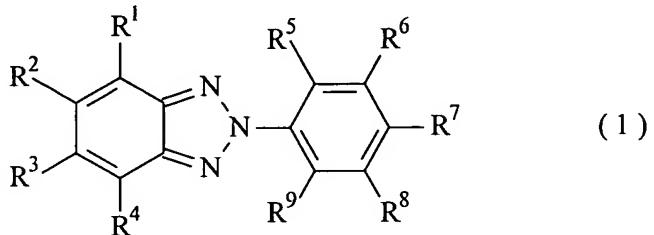


CLAIMS

1. An improver for adhesion of a photosensitive resin composition to a substrate, which consists of an N-phenyl-2H-benzotriazole compound represented by the general formula (1):



wherein R¹ to R⁴ each independently represent a hydrogen atom, a halogen atom or a C₁₋₅ alkyl group; R⁵ to R⁹ each independently represent a hydrogen atom, a hydroxyl group, a C₁₋₁₀ alkyl group, an aryl group, a C₇₋₁₂ aralkyl group, -R¹⁰COOR¹¹, or -R¹⁰CO-(OCH₂CH₂)_n-OH provided that at least one of R⁵ and R⁹ is a hydroxyl group; R¹⁰ represents a C₂₋₅ alkylene group; R¹¹ represents a C₁₋₈ alkyl group; and n is an integer of 2 to 20.

2. A photosensitive resin composition containing an alkali-soluble resin and a photosensitizer, which comprises at least one of N-phenyl-2H-benzotriazole compounds represented by the general formula (1) in claim 1.

3. The photosensitive resin composition according to claim 2, wherein the alkali-soluble resin is novolak resin, and the photosensitizer is a compound containing a quinonediazide group.